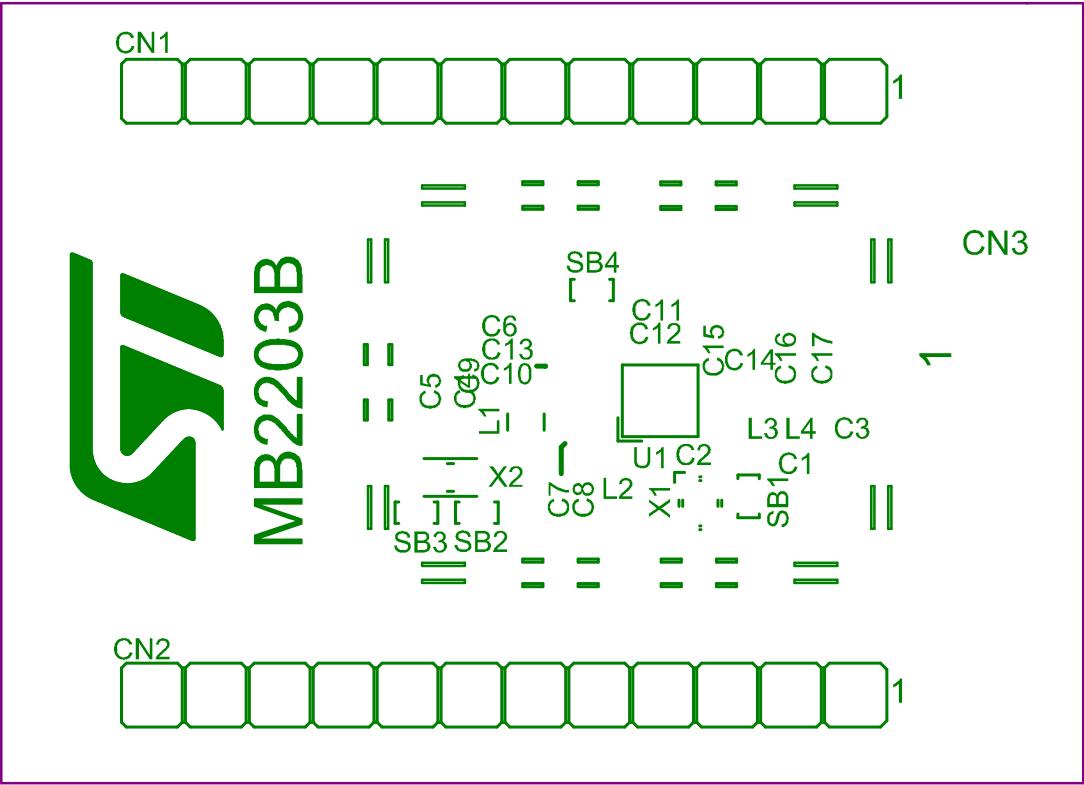
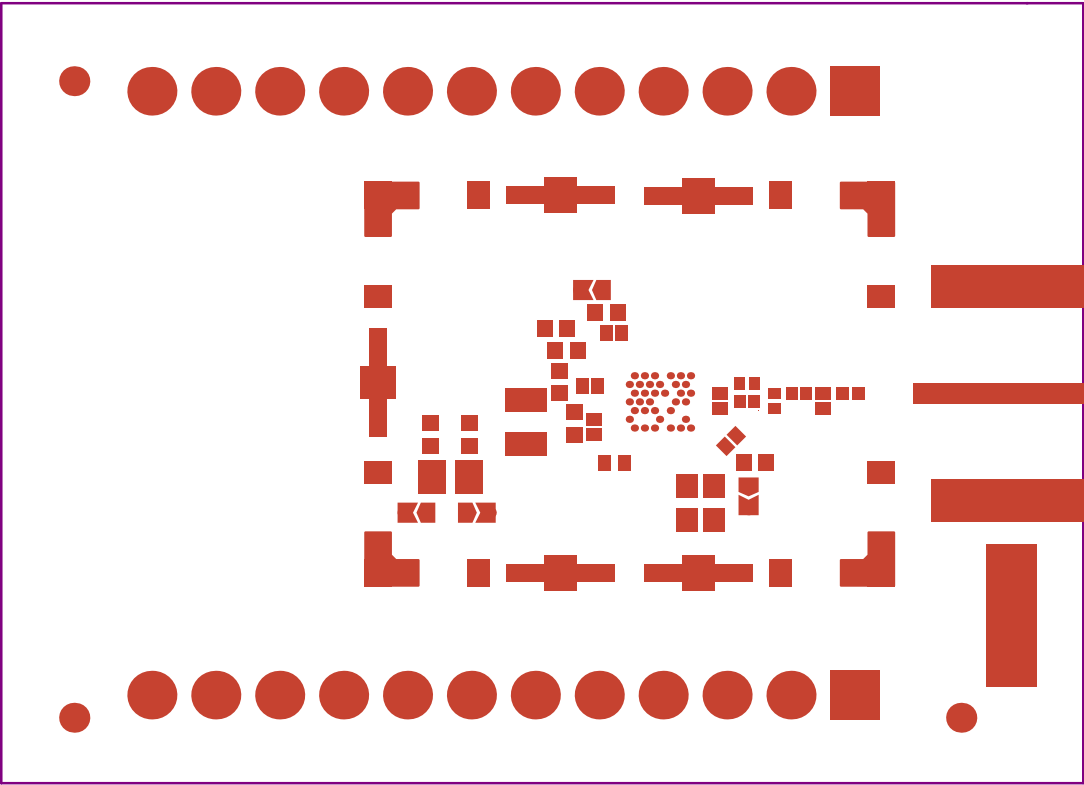
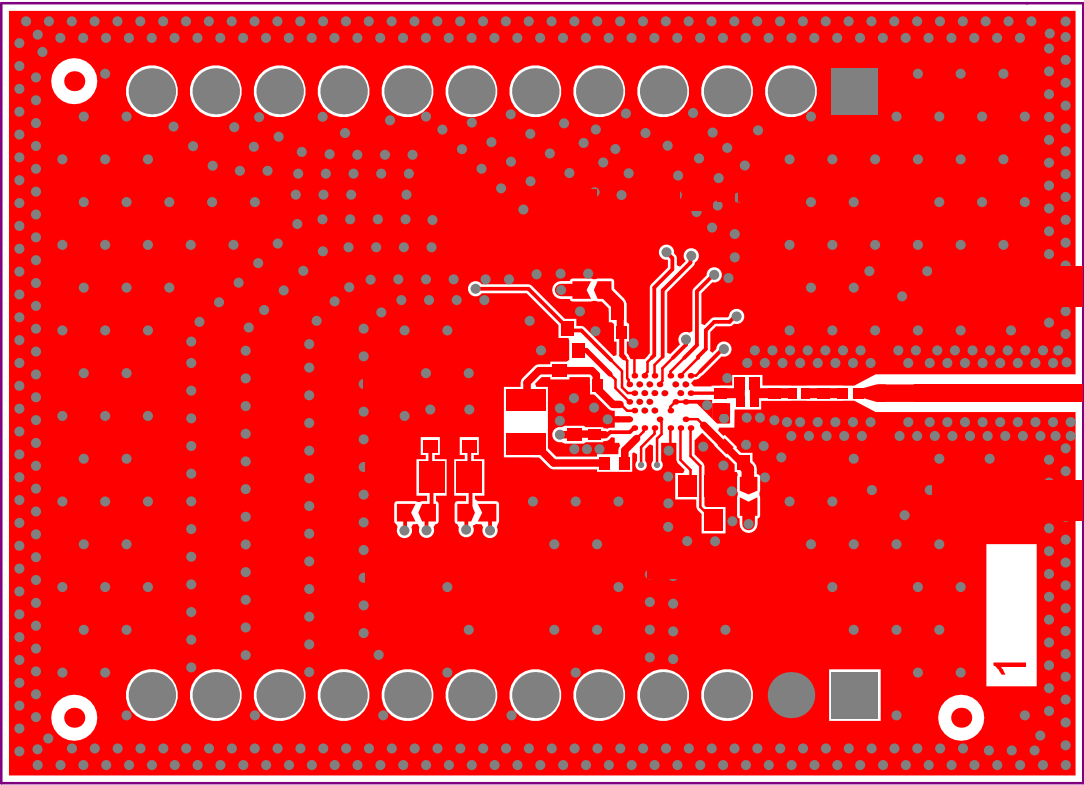




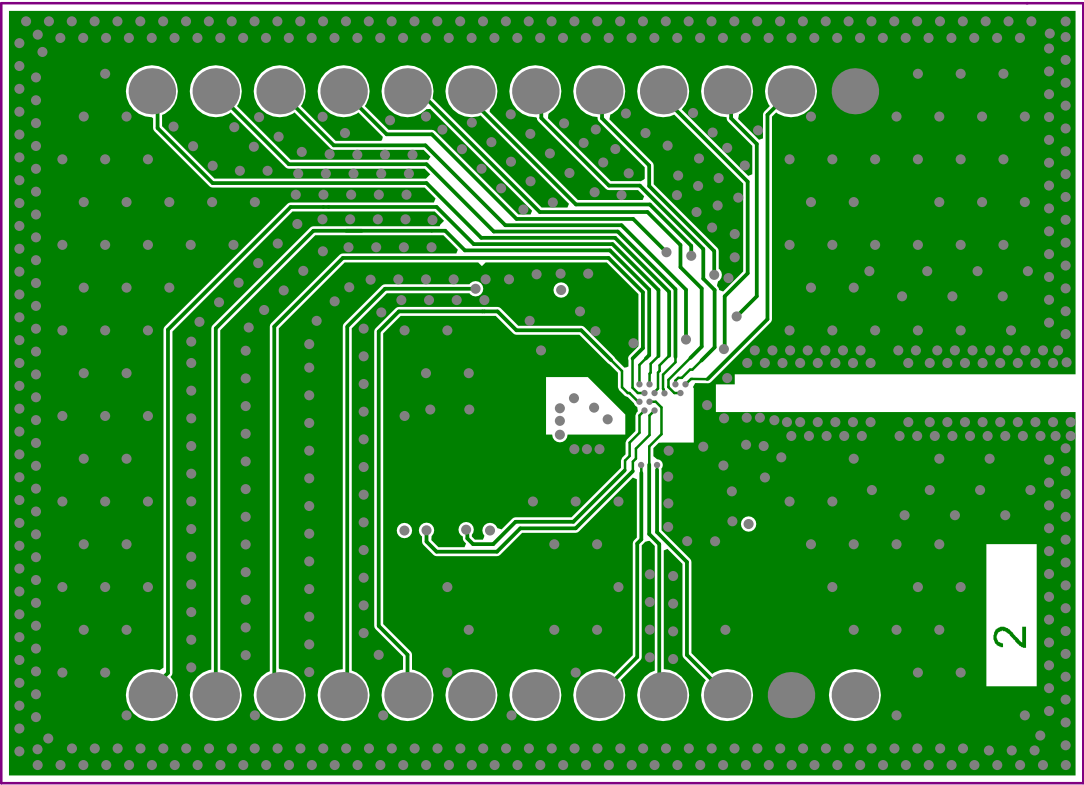
Project: Reference design for STM32WB09 - Discrete		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	MB2203	
Date: 13-OCT-2025	Rev: B	



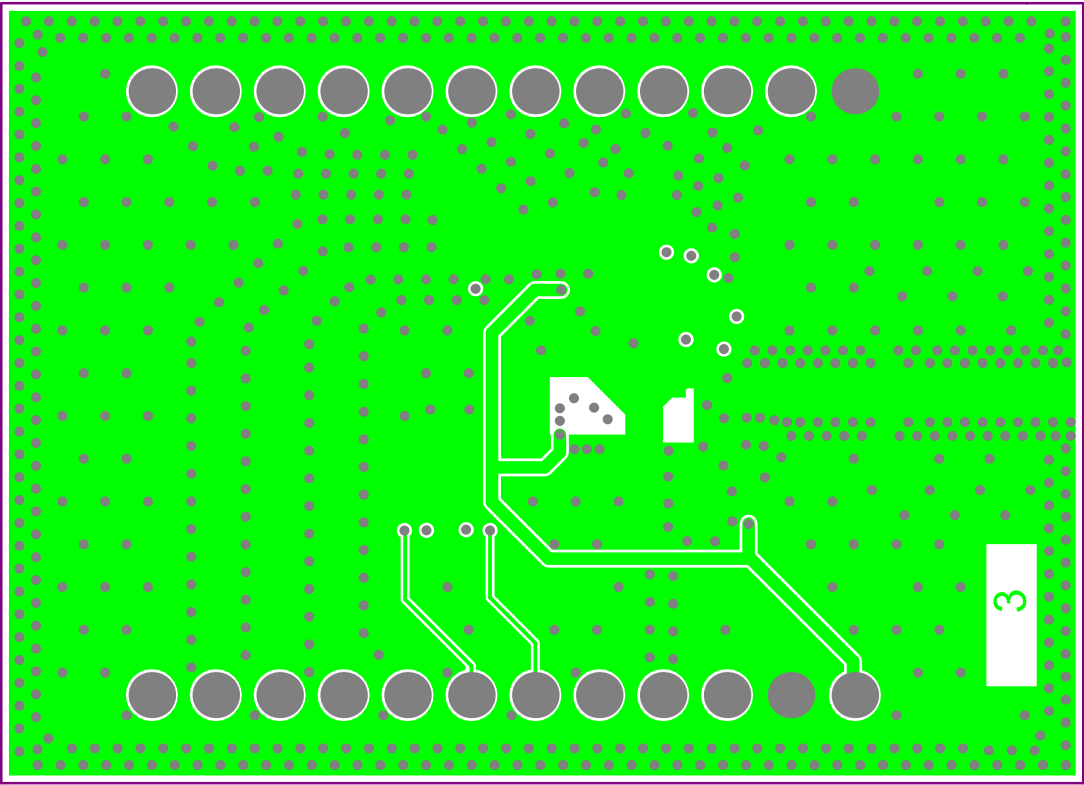
Project: Reference design for STM32WB09 - Discrete		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	MB2203	
Date: 13-OCT-2025	Rev: B	



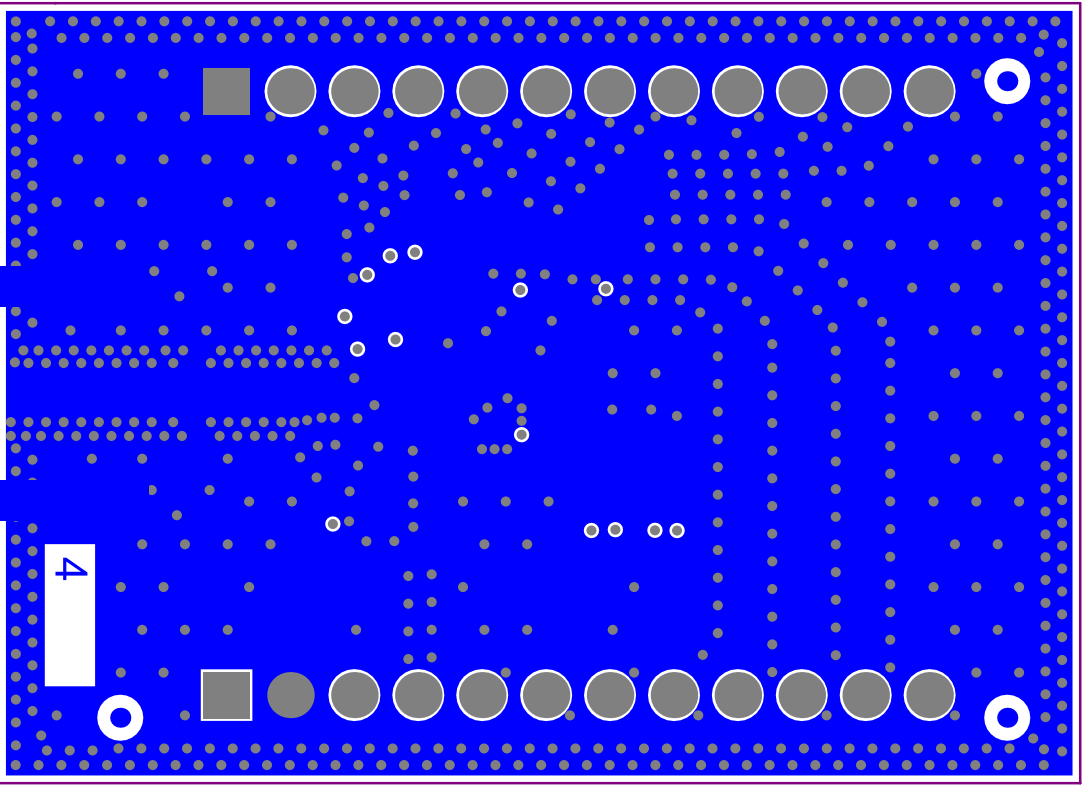
Project: Reference design for STM32WB09 - Discrete		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	MB2203	
Date: 13-OCT-2025	Rev: B	



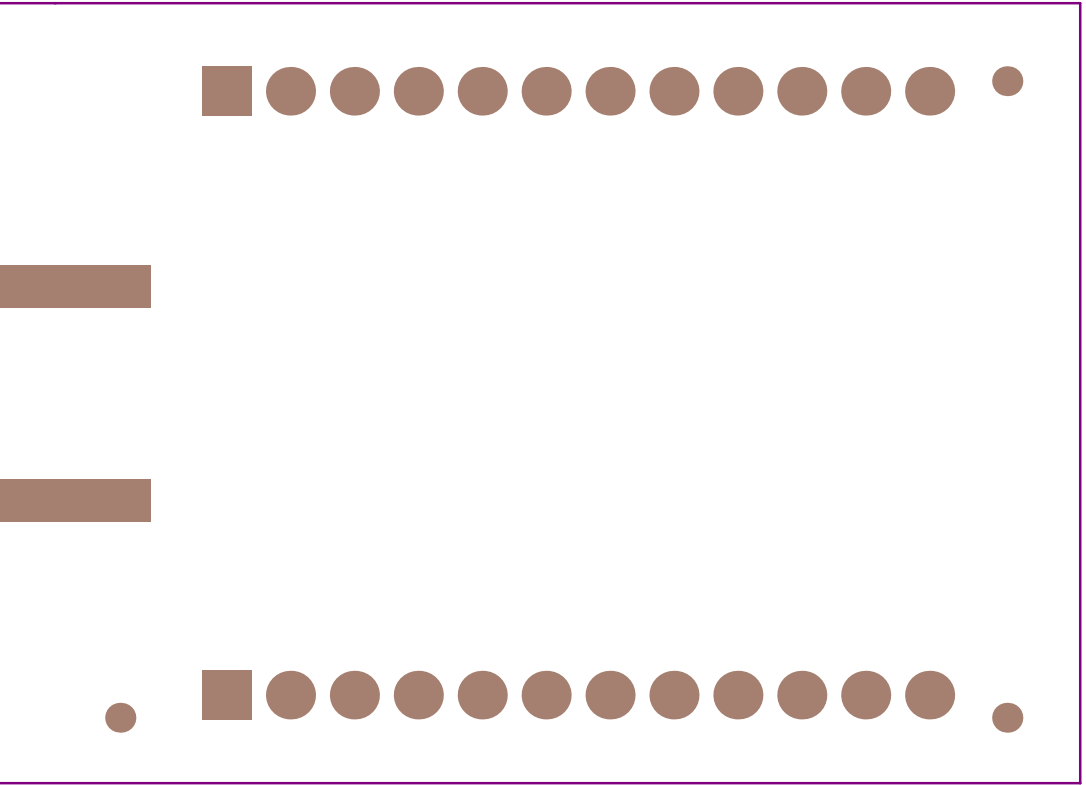
Project: Reference design for STM32WB09 - Discrete		
Layer: Signal Layer 1	Gerber: .G1	
Variant: [No Variations]	MB2203	
Date: 13-OCT-2025	Rev: B	



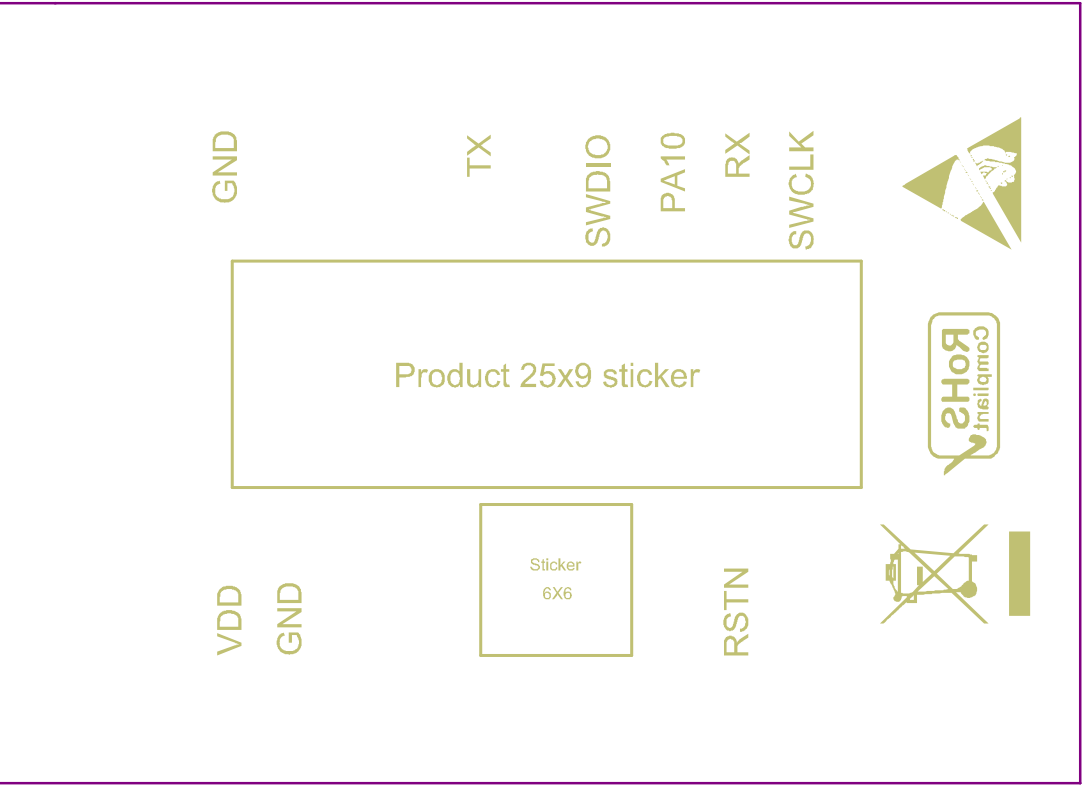
Project: Reference design for STM32WB09 - Discrete		
Layer: Signal Layer 2	Gerber: .G2	
Variant: [No Variations]	MB2203	
Date: 13-OCT-2025	Rev: B	



Project: Reference design for STM32WB09 - Discrete		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	MB2203	
Date: 13-OCT-2025	Rev: B	



Project: Reference design for STM32WB09 - Discrete		
Layer: Bottom Solder	Gerber: .GBS	
Variant: [No Variations]	MB2203	
Date: 13-OCT-2025	Rev: B	

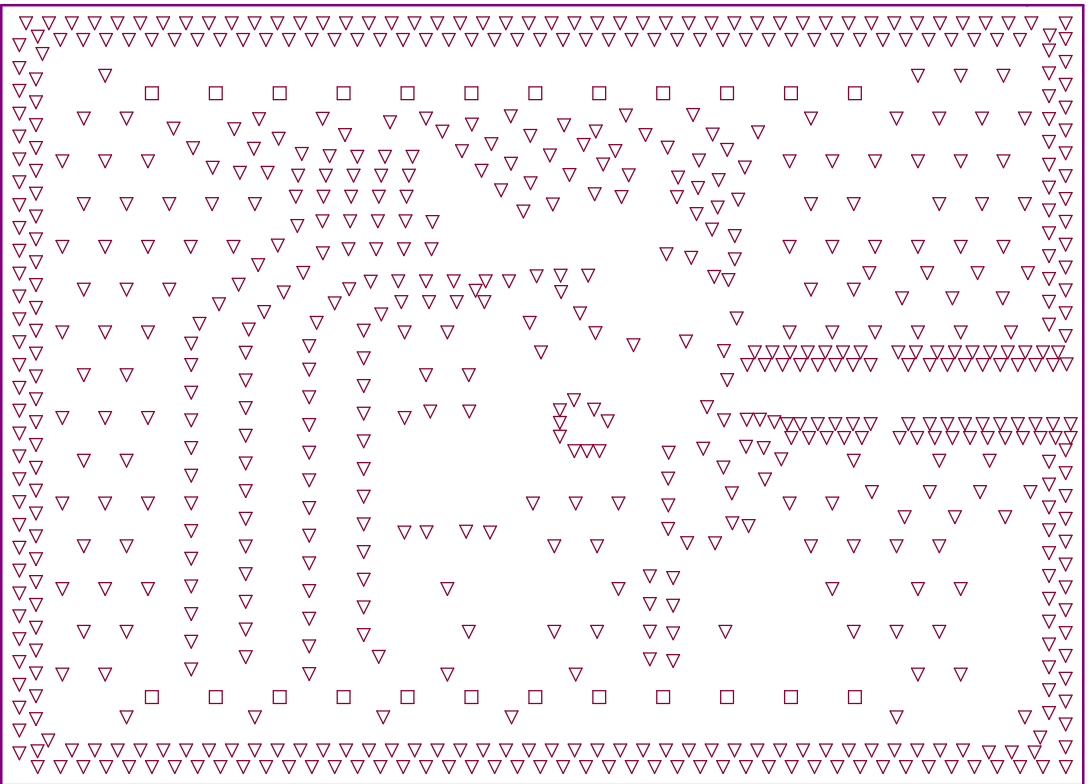


Project: Reference design for STM32WB09 - Discrete		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	MB2203	
Date: 13-OCT-2025	Rev: B	

A. MATERIAL :	FR-4	☐ TG-170	☒ TG-150	☐ TG-140
B. MATERIAL FAMILY :	N/A			
C. SOLDERMASK COLOR :	☐ GREEN	☒ WHITE	☐ RED	☐ BLACK
D. SILKSCREEN COLOR :	☐ WHITE	☐ YELLOW	☐ BLACK	☒ Blue ink PANTONE 2955
E. SURFACE FINISH :	☒ ENIG	☐ IMMERSION SILVER	☐ IMMERSION TIN	
	☐ HASL	☐ HASL (PB-FREE)	☐ GOLDEN FINGER	
F. IMPEDANCE CONTROL :	☐ NO	☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)		
G. THROUGH VIA :	PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.			
	PLUG MATERIAL :		☒ SOLDERMASK	☐ NON-CONDUCTIVE EPOXY.
H. STACK-UP :	SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.			

ASPECT-RATIO, AXE Z :
6:1 to 8:1
LEVEL "B"

DEFAULT
TRACKS : 0.1mm
GAPS : 0.1mm



Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	0,020mm	3.5
1	Top Layer		0,035mm	
	Dielectric 1	TU-768 (1x2113)	0,102mm	4.2
2	Signal Layer 1		0,036mm	
	Dielectric2	Tu-768 (2x2113)	0,254mm	4.3
3	Signal Layer 2		0,036mm	
	Dielectric3	TU-768 (1x2113)	0,102mm	4.2
4	Bottom Layer		0,035mm	
	Bottom Solder	Solder Resist	0,020mm	3.5
	Bottom Overlay			

Total board thickness: 0,639mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Hole Length	Routed Path Length
	14	0.100mm (3.94mil)	PTH	Round	[uVia] Top Layer - Signal Layer 1	Via	Rounded	v25h10m0	-	-
	24	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)	-	-
	709	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)	-	-
	747 Total									

Project: Reference design for STM32WB09 - Discrete		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	MB2203	
Date: 13-OCT-2025	Rev: B	